



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20180411001.1
Qualification of RFAB for select devices in the LBC8LV process technology
Change Notification / Sample Request

Date: April 16, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20180411001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS131A02IPBSR	null
ADS131A04IPBSR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180411001.1	PCN Date:	Apr 16, 2018
Title:	Qualification of RFAB for select devices in the LBC8LV process technology		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jul 16, 2018	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional wafer fab site option for the LBC8LV devices listed in the product affected section of this document.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	LBC8LV	200 mm	RFAB	LBC8LV	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT: 39
 ITEM:
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHP (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

ADS131A02IPBS	ADS131A02IPBSR	ADS131A04IPBS	ADS131A04IPBSR
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Qualification Report

ADS131A02IPBS and ADS131A04IPBS offload from DMO5 to RFAB Approve Date 11-Dec-2017

Product Attributes

Attributes	Qual Device: ADS131A02IPBS	Qual Device: ADS131A04IPBS	QBS Process Reference: TMP468AIYFF	QBS Package Reference: ADS131A04IPBS
Assembly Site	TAI	TAI	CLARK	TAI
Package Family	TQFP	TQFP	DSBGA	TQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB	DM5
Wafer Process	LBC8LV	LBC8LV	LBC8LV	LBC8LV

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL2-260C: ADS131A02IPBS, ADS131A04IPBS

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS131A02IPBS	Qual Device: ADS131A04IPBS	QBS Process Reference: TMP468AIYFF	QBS Package Reference: ADS131A04IPBS
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/227/0	3/231/0
HBM	ESD - HBM	2500 V	-	1/3/0	2/6/0	-
CDM	ESD - CDM	1000 V	-	1/3/0	3/9/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-
LU	Latch-up	(per JESD78)	-	1/6/0	1/6/0	1/12/0
PD	Physical Dimensions	--	-	-	3/60/0	-
SD	Surface Mount Solderability	Pb Free	-	-	3/108/0	-
SBS	WCSP Solder Ball Shear	--	-	-	3/150/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	3/230/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com